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CERTIFICATE OF TAPPlicant(s): Alcoe et al.	TRANSMISSION BY FACS	SIMILE (37 CFR 1.8)	Docket No. END920010135US2
Application No. 10/665,669	Filing Date 9/18/2003	Examiner Thao, X. Le	Group Art Unit 2814
Invention: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES			
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I hereby certify that this Request for Reconsideration (13 pages) (Identify type of correspondence)			
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/665,669

Applicant(s): Alcoe et al.

Filed.: September 18, 2003

Art Unit: 2814

Dkt. No.: END920010135US2

Examiner: Le, Thao X.

Title: ENHANCED LID FOR MULTI-CHIP MODULES

Honorable Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

REQUEST FOR RECONSIDERATION

This Request for Reconsideration is being filed in response to the Office Action mailed on January 3, 2006.